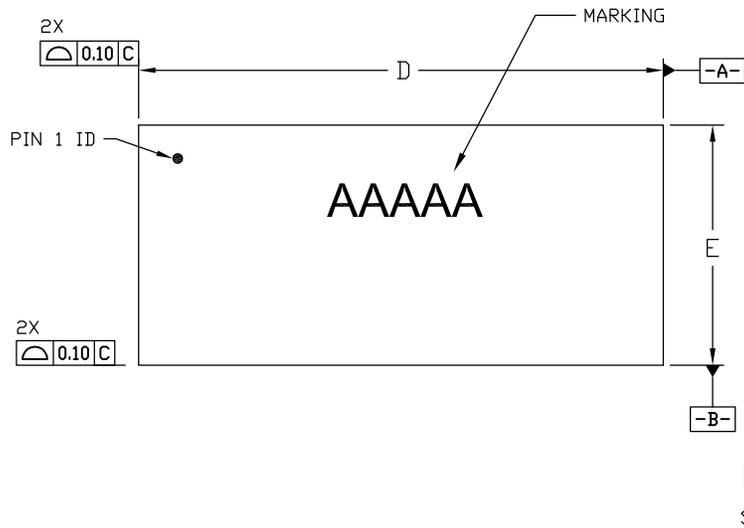
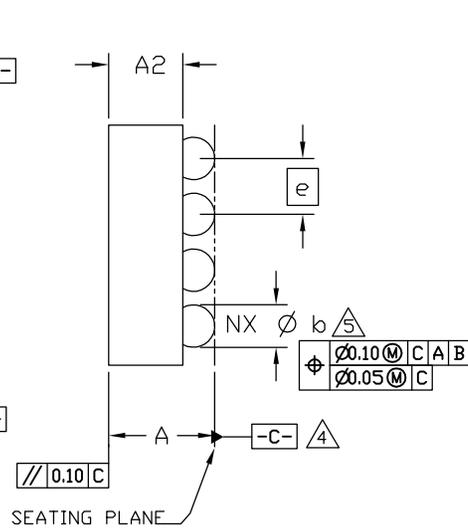


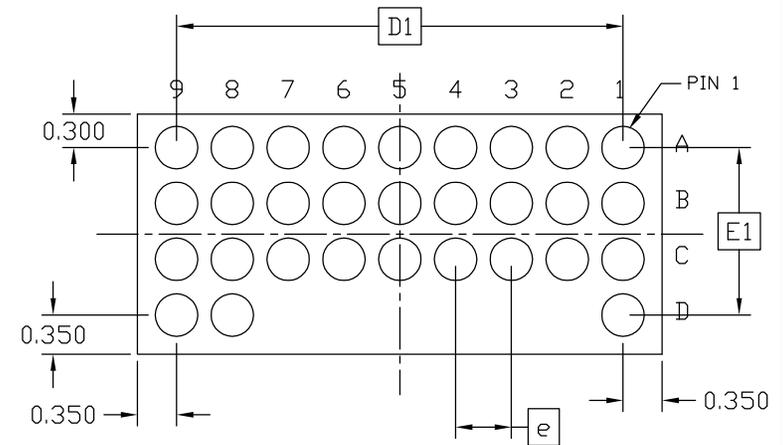
TOP VIEW



SIDE VIEW



BOTTOM VIEW



NOTES:

1. ALL DIMENSIONS ARE IN MILLIMETERS.
2. MD IS THE BALL MATRIX SIZE IN THE "D" DIRECTION, ME IS THE BALL MATRIX SIZE IN THE "E" DIRECTION, AND N IS THE TOTAL NUMBER OF BALLS FOR THE MATRIX SIZE MD X ME AND DOES NOT INCLUDE BALLS FROM ANY DEPOPULATED LOCATIONS.
3. DIMENSIONING AND TOLERANCING CONFORM TO ASME Y14.5M-1994.
4. PRIMARY DATUM C (SEATING PLANE) IS DEFINED BY THE CROWNS OF THE SOLDER BALLS.
5. DIMENSION b IS MEASURED AT THE MAXIMUM SOLDER BALL DIAMETER IN A PLANE PARALLEL TO DATUM C.
6. MARKING SHOWN IS FOR PKG. ORIENTATION PURPOSE ONLY.
7. MATERIAL MUST COMPLY WITH BANNED AND RESTRICTED SUBSTANCES SPEC #10-0131.
8. ALL DIMENSIONS APPLY TO BOTH LEADED(-) AND PbFREE (+) PKG. CODES.

DIM	MILLIMETERS			INCHES		
	MIN	NOM	MAX	MIN	NOM	MAX
A	-	0.950	-	-	.037	-
A2	0.640	-	0.690	.025	-	.027
b	0.380 BSC			.015 BSC		
D	4.600	-	4.700	.181	-	.185
D1	4.000 BSC			.157 BSC		
E	2.100	-	2.250	.083	-	.089
E1	1.500 BSC			.059 BSC		
e	0.500 BSC			.020 BSC		
MD	-	-	9 BALLS	-	-	9 BALLS
ME	-	-	4 BALLS	-	-	4 BALLS
N	30 BALLS			30 BALLS		



TITLE:
PACKAGE OUTLINE, 30 BALLS
WLCSP PKG. 0.50mm PITCH, C304A2+1

APPROVAL	DOCUMENT CONTROL NO. 21-0930	REV. A	1/1
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-DRAWING NOT TO SCALE-